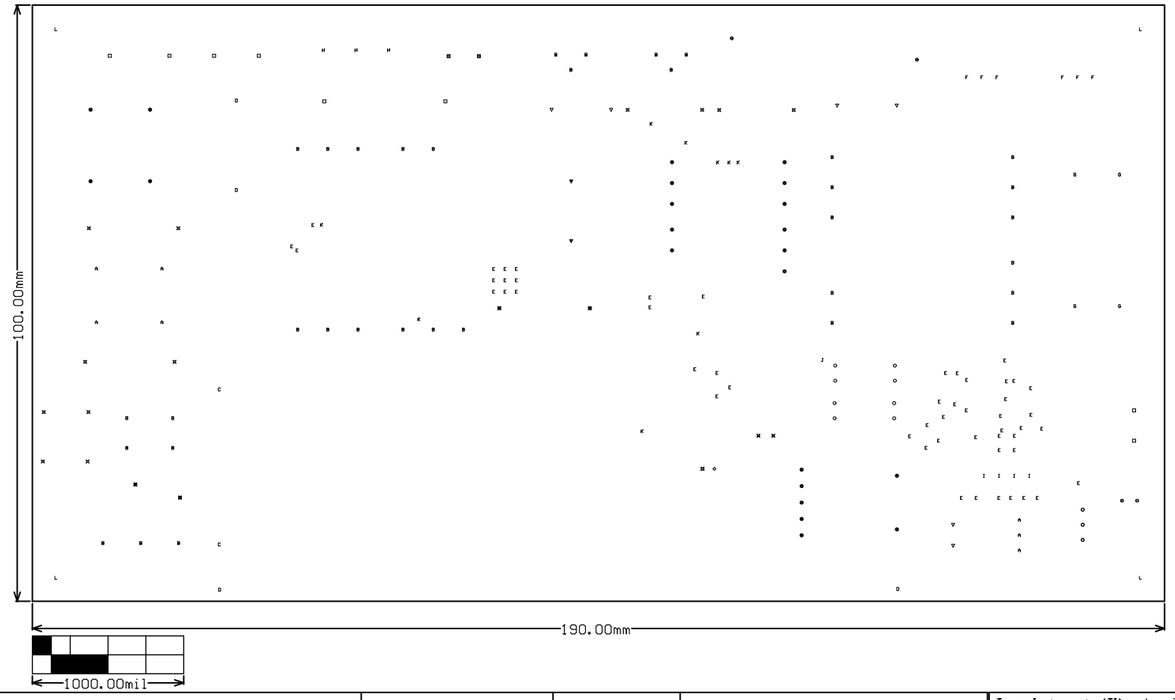
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		2.80mil		
	Dielectric1	FR-4	59.20mil	4.8	
2	Bottom Layer		2.80mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
K	9	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
E	52	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
O	8	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	
◇	1	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	1	28.01mil (0.712mm)	PTH	Round	Top Layer - Bottom Layer	
✪	3	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
✖	2	31.00mil (0.787mm)	PTH	Round	Top Layer - Bottom Layer	
▽	6	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	12	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
D	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
I	4	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
C	2	41.00mil (1.041mm)	PTH	Round	Top Layer - Bottom Layer	
G	4	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
✡	2	42.91mil (1.090mm)	PTH	Round	Top Layer - Bottom Layer	
✖	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
✪	22	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	2	47.24mil (1.200mm)	PTH	Rectangle	Top Layer - Bottom Layer	
A	7	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
F	6	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
B	35	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
▣	2	55.12mil (1.400mm)	PTH	Round	Top Layer - Bottom Layer	
H	3	62.00mil (1.575mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
J	1	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
L	4	125.98mil (3.200mm)	NPTH	Round	Top Layer - Bottom Layer	
	206 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL WAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL WAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: 500W PFC+LLC+FLYBACK Charger
DESIGNED FOR: Public Release
FILE NAME: PCB_Project_PMP23464_PCB.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23464	REV: A	SUN REV: Not in version control
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 2/26/2024 1:13:20 PM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
B Lough	M Olinde
SCALE: 1.00	ALTIUM DESIGNER VERSION: 23.1.1.15